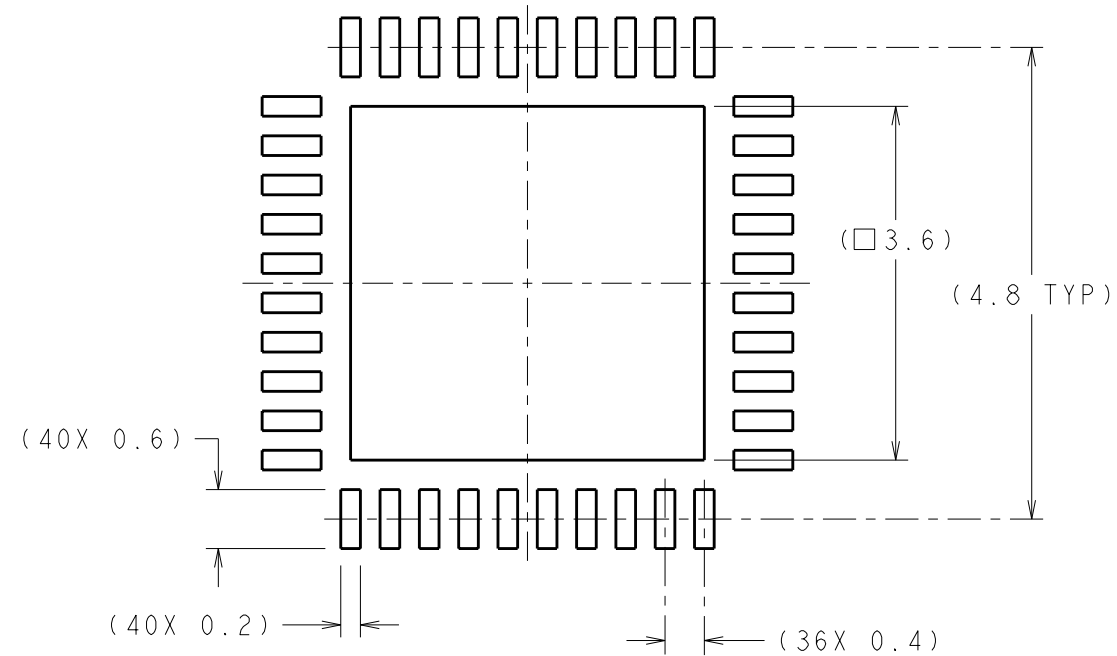
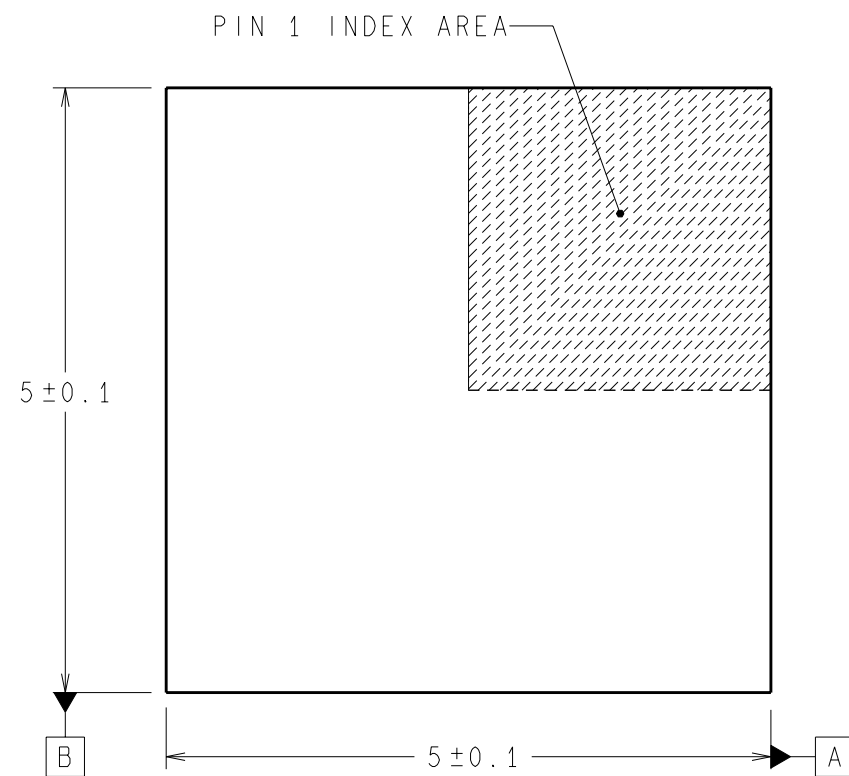


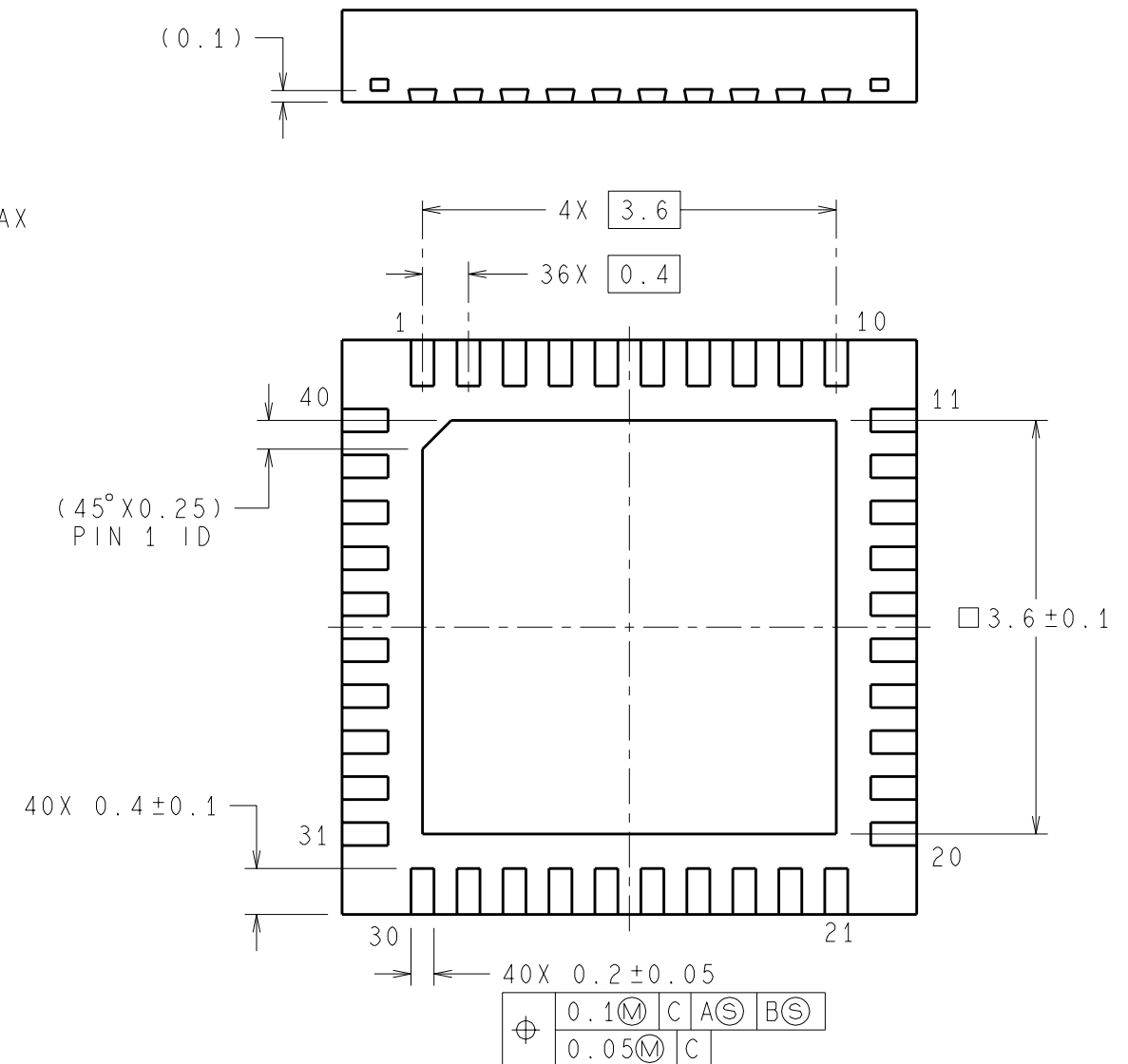
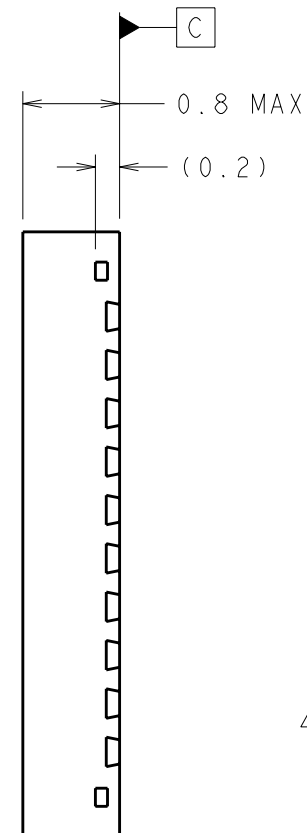
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1466	04/30/2004	TL/JS
B	CORRECT LEAD NUMBERING TYPO; UPDATE NOTE 3	1546	07/06/2004	TL/JS



RECOMMENDED LAND PATTERN



DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- MAXIMUM ALLOWABLE METAL BURR ON LEAD TIPS AT THE PACKAGE EDGES IS 76 MICRONS.
- NO JEDEC REGISTRATION AS OF JULY 2004.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DRAWN	T. LEQUANG	04/30/2004			
DFTG. CHK.	MARTA SUCHY	07/06/2004	LLP, QUAD, 5x5x0.8mm, 40 LD, 0.4mm PITCH, 3.6x3.6mm EXP PAD		
ENGR. CHK.	JEFF SCHAEFER	07/06/2004			
PROJECTION	MM	SCALE	SIZE	DRAWING NUMBER	REV
		NTS	B	(SC)MKT-SQF40A	B
FORMERLY: X-01983		SHEET 1 of 1			